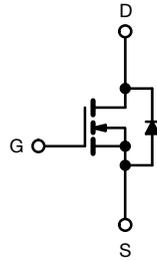
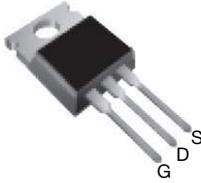


## Power MOSFET

**TO-220AB**


N-Channel MOSFET

### FEATURES

- Low gate charge  $Q_g$  results in simple drive requirement
- Improved gate, avalanche, and dynamic  $dV/dt$  ruggedness
- Fully characterized capacitance and avalanche voltage and current
- Material categorization: for definitions of compliance please see [www.vishay.com/doc?99912](http://www.vishay.com/doc?99912)


**RoHS\***  
Available

### Note

\* This datasheet provides information about parts that are RoHS-compliant and / or parts that are non RoHS-compliant. For example, parts with lead (Pb) terminations are not RoHS-compliant. Please see the information / tables in this datasheet for details

### APPLICATIONS

- Switch mode power supply (SMPS)
- Uninterruptible power supply
- High speed power switching

### APPLICABLE OFF LINE SMPS TOPOLOGIES

- Two transistor forward
- Half and full bridge
- Power factor correction boost

### PRODUCT SUMMARY

$V_{DS}$ (V)	500	
$R_{DS(on)}$ ( $\Omega$ )	$V_{GS} = 10\text{ V}$	0.52
$Q_g$ max. (nC)	52	
$Q_{gs}$ (nC)	13	
$Q_{gd}$ (nC)	18	
Configuration	Single	

### ORDERING INFORMATION

Package	TO-220
Lead (Pb)-free	IRFB11N50APbF
Lead (Pb)-free and halogen-free	IRFB11N50APbF-BE3

### ABSOLUTE MAXIMUM RATINGS ( $T_C = 25\text{ }^\circ\text{C}$ , unless otherwise noted)

PARAMETER	SYMBOL	LIMIT	UNIT
Drain-source voltage	$V_{DS}$	500	V
Gate-source voltage	$V_{GS}$	$\pm 30$	
Continuous drain current	$I_D$	$V_{GS}$ at 10 V	A
		$T_C = 25\text{ }^\circ\text{C}$	
		$T_C = 100\text{ }^\circ\text{C}$	7.0
Pulsed drain current <sup>a</sup>	$I_{DM}$	44	
Linear derating factor		1.3	W/ $^\circ\text{C}$
Single pulse avalanche energy <sup>b</sup>	$E_{AS}$	275	mJ
Repetitive avalanche current <sup>a</sup>	$I_{AR}$	11	A
Repetitive avalanche energy <sup>a</sup>	$E_{AR}$	17	mJ
Maximum power dissipation	$P_D$	170	W
		$T_C = 25\text{ }^\circ\text{C}$	
Peak diode recovery $dV/dt$ <sup>c</sup>	$dV/dt$	6.9	V/ns
Operating junction and storage temperature range	$T_J, T_{stg}$	-55 to +150	$^\circ\text{C}$
Soldering recommendations (peak temperature) <sup>d</sup>	For 10 s	300	
Mounting torque	6-32 or M3 screw		10
			1.1
			lbf · in
			N · m

### Notes

- Repetitive rating; pulse width limited by maximum junction temperature (see fig. 11)
- Starting  $T_J = 25\text{ }^\circ\text{C}$ ,  $L = 4.5\text{ mH}$ ,  $R_G = 25\text{ }^\circ\Omega$ ,  $I_{AS} = 11\text{ A}$  (see fig. 12)
- $I_{SD} \leq 11\text{ A}$ ,  $dI/dt \leq 140\text{ A}/\mu\text{s}$ ,  $V_{DD} \leq V_{DS}$ ,  $T_J \leq 150\text{ }^\circ\text{C}$
- 1.6 mm from case



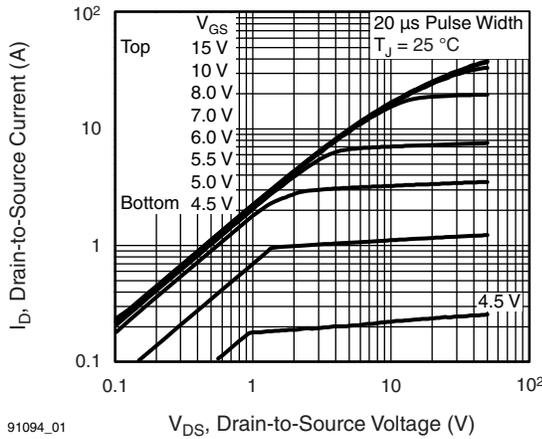
THERMAL RESISTANCE				
PARAMETER	SYMBOL	TYP.	MAX.	UNIT
Maximum junction-to-ambient	$R_{thJA}$	-	62	°C/W
Case-to-sink, flat, greased surface	$R_{thCS}$	0.50	-	
Maximum junction-to-case (drain)	$R_{thJC}$	-	0.75	

SPECIFICATIONS ( $T_J = 25\text{ }^\circ\text{C}$ , unless otherwise noted)							
PARAMETER	SYMBOL	TEST CONDITIONS	MIN.	TYP.	MAX.	UNIT	
<b>Static</b>							
Drain-source breakdown voltage	$V_{DS}$	$V_{GS} = 0\text{ V}, I_D = 250\text{ }\mu\text{A}$	500	-	-	V	
Gate-source threshold voltage	$V_{GS(th)}$	$V_{DS} = V_{GS}, I_D = 250\text{ }\mu\text{A}$	2.0	-	4.0	V	
Gate-source leakage	$I_{GSS}$	$V_{GS} = \pm 30\text{ V}$	-	-	$\pm 100$	nA	
Zero gate voltage drain current	$I_{DSS}$	$V_{DS} = 500\text{ V}, V_{GS} = 0\text{ V}$	-	-	25	$\mu\text{A}$	
		$V_{DS} = 400\text{ V}, V_{GS} = 0\text{ V}, T_J = 150\text{ }^\circ\text{C}$	-	-	250		
Drain-source on-state resistance	$R_{DS(on)}$	$V_{GS} = 10\text{ V}, I_D = 6.6\text{ A}^b$	-	-	0.52	$\Omega$	
Forward transconductance	$g_{fs}$	$V_{DS} = 50\text{ V}, I_D = 6.6\text{ A}$	6.1	-	-	S	
<b>Dynamic</b>							
Input capacitance	$C_{iss}$	$V_{GS} = 0\text{ V}, V_{DS} = 25\text{ V}, f = 1.0\text{ MHz}, \text{ see fig. 5}$	-	1423	-	pF	
Output capacitance	$C_{oss}$		-	208	-		
Reverse transfer capacitance	$C_{rss}$		-	8.1	-		
Output capacitance	$C_{oss}$	$V_{GS} = 0\text{ V}$	$V_{DS} = 1.0\text{ V}, f = 1.0\text{ MHz}$	-	2000	-	
Effective output capacitance	$C_{oss\text{ eff.}}$		$V_{DS} = 400\text{ V}, f = 1.0\text{ MHz}$	-	55	-	
Total gate charge	$Q_g$	$V_{GS} = 10\text{ V}$	$V_{DS} = 0\text{ V to } 400\text{ V}$	-	97	-	
Gate-source charge	$Q_{gs}$		$I_D = 11\text{ A}, V_{DS} = 400\text{ V}$ see fig. 6 and 13 <sup>b</sup>	-	-	52	nC
Gate-drain charge	$Q_{gd}$			-	-	13	
Turn-on delay time	$t_{d(on)}$	$V_{DD} = 250\text{ V}, I_D = 11\text{ A}$ $R_G = 9.1\text{ }\Omega, R_D = 22\text{ }\Omega, \text{ see fig. 10}^b$	-	14	-	ns	
Rise time	$t_r$		-	35	-		
Turn-off delay time	$t_{d(off)}$		-	32	-		
Fall time	$t_f$		-	28	-		
Gate input resistance	$R_g$	$f = 1\text{ MHz}, \text{ open drain}$	0.5	-	3.2	$\Omega$	
<b>Drain-Source Body Diode Characteristics</b>							
Continuous source-drain diode current	$I_S$	MOSFET symbol showing the integral reverse p - n junction diode 	-	-	11	A	
Pulsed diode forward current <sup>a</sup>	$I_{SM}$		-	-	44		
Body diode voltage	$V_{SD}$	$T_J = 25\text{ }^\circ\text{C}, I_S = 11\text{ A}, V_{GS} = 0\text{ V}^b$	-	-	1.5	V	
Body diode reverse recovery time	$t_{rr}$	$T_J = 25\text{ }^\circ\text{C}, I_F = 11\text{ A}, dI/dt = 100\text{ A}/\mu\text{s}^b$	-	510	770	ns	
Body diode reverse recovery charge	$Q_{rr}$		-	3.4	5.1	$\mu\text{C}$	
Forward turn-on time	$t_{on}$	Intrinsic turn-on time is negligible (turn-on is dominated by $L_S$ and $L_D$ )					

**Notes**

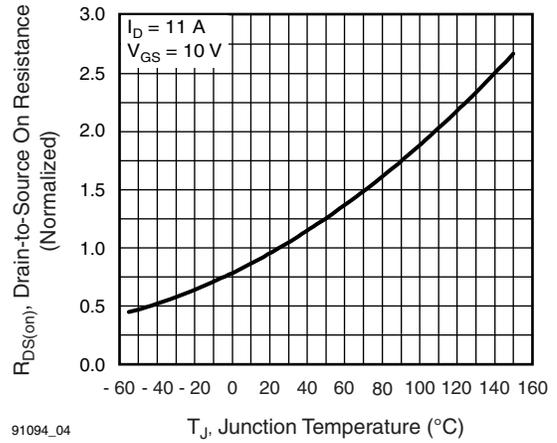
- a. Repetitive rating; pulse width limited by maximum junction temperature (see fig. 11)
- b. Pulse width  $\leq 300\text{ }\mu\text{s}$ ; duty cycle  $\leq 2\%$
- c.  $C_{oss\text{ eff.}}$  effective is a fixed capacitance that gives the same charging time as  $C_{oss}$  while  $V_{DS}$  is rising from 0 % to 80 %  $V_{DS}$

**TYPICAL CHARACTERISTICS** (25 °C, unless otherwise noted)



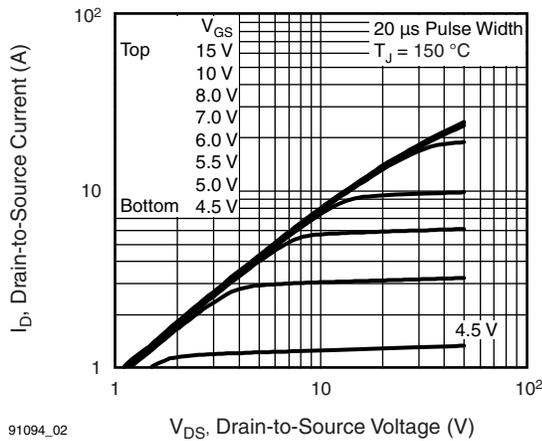
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**Fig. 1 - Typical Output Characteristics**



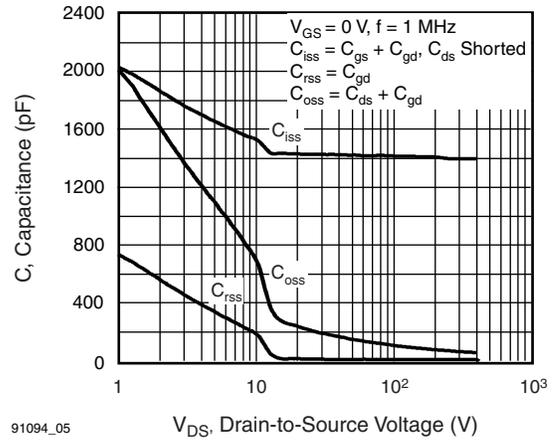
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**Fig. 4 - Normalized On-Resistance vs. Temperature**



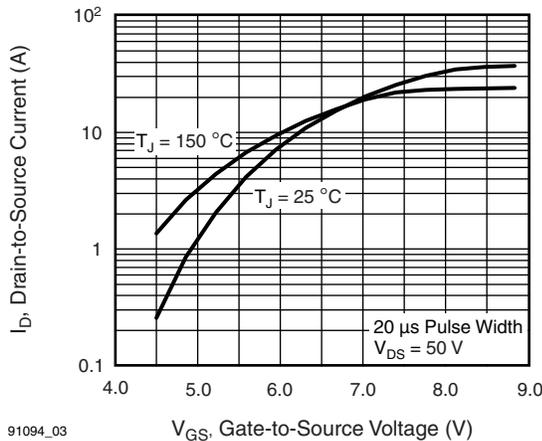
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**Fig. 2 - Typical Output Characteristics**



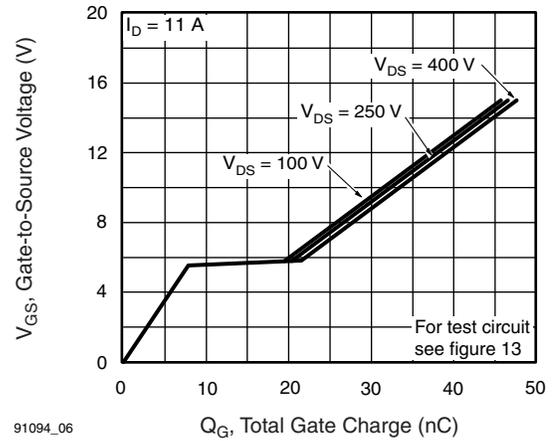
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**Fig. 5 - Typical Capacitance vs. Drain-to-Source Voltage**



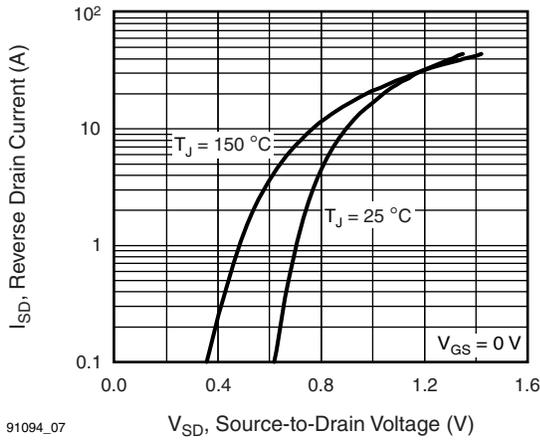
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**Fig. 3 - Typical Transfer Characteristics**

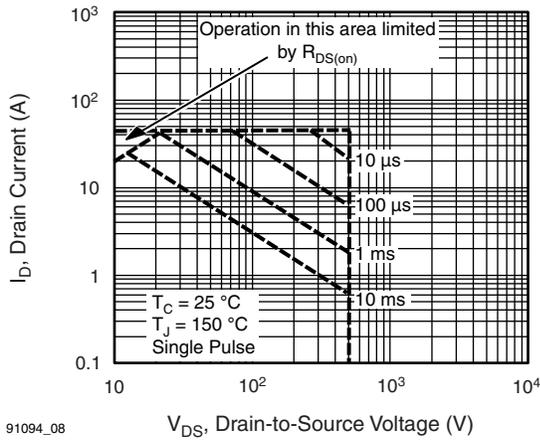


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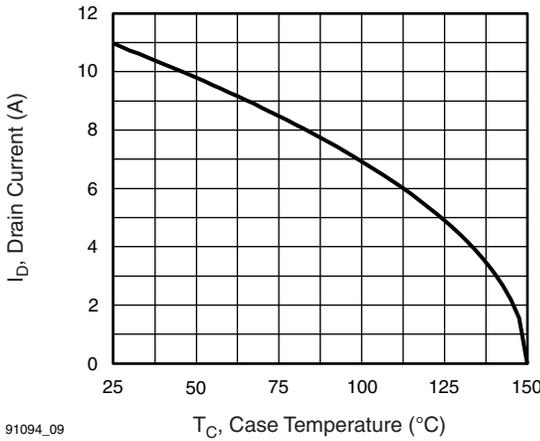
**Fig. 6 - Typical Gate Charge vs. Gate-to-Source Voltage**



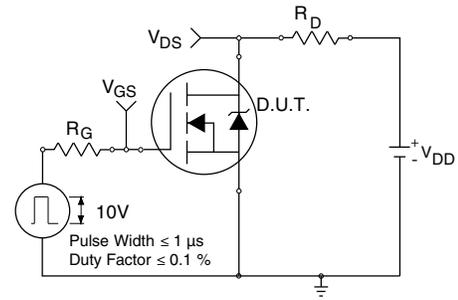
**Fig. 7 - Typical Source-Drain Diode Forward Voltage**



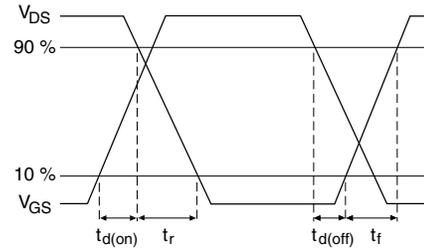
**Fig. 8 - Maximum Safe Operating Area**



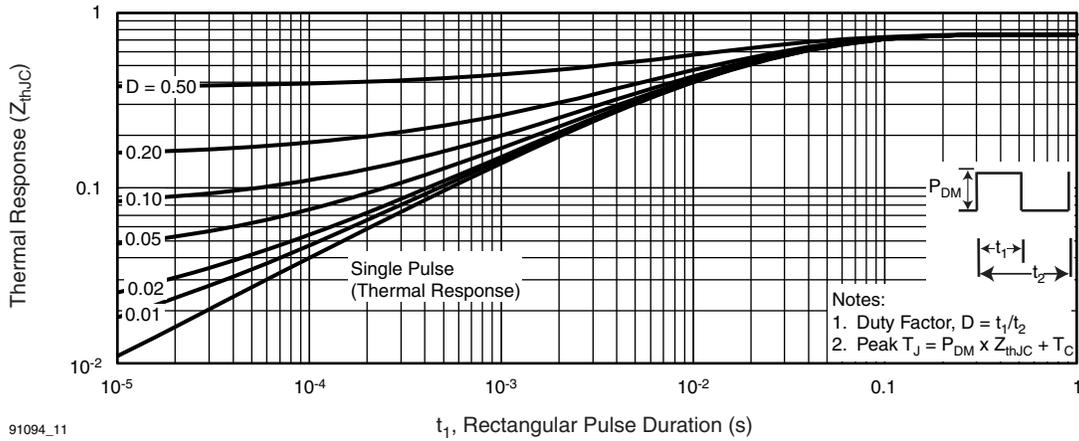
**Fig. 9 - Maximum Drain Current vs. Case Temperature**



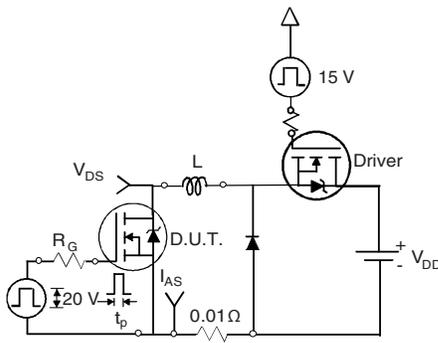
**Fig. 10a - Switching Time Test Circuit**



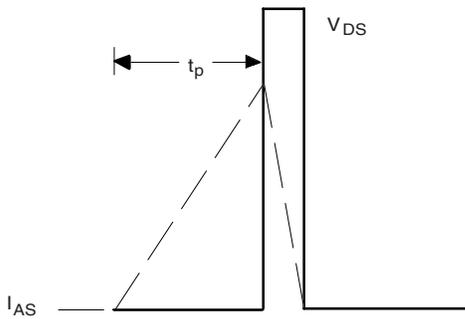
**Fig. 10b - Switching Time Waveforms**



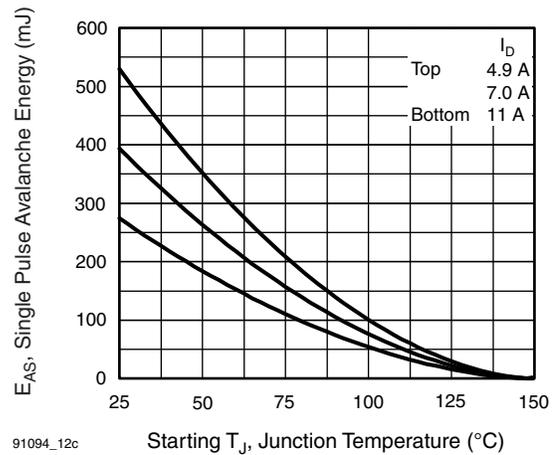
**Fig. 11 - Maximum Effective Transient Thermal Impedance, Junction-to-Case**



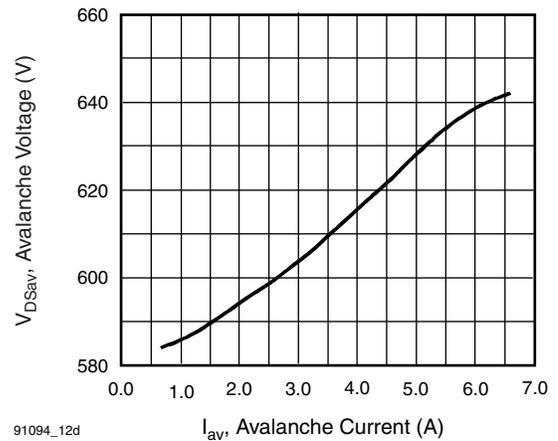
**Fig. 12a - Unclamped Inductive Test Circuit**



**Fig. 12b - Unclamped Inductive Waveforms**



**Fig. 12c - Maximum Avalanche Energy vs. Drain Current**



**Fig. 12d - Typical Drain-to-Source Voltage vs. Avalanche Current**

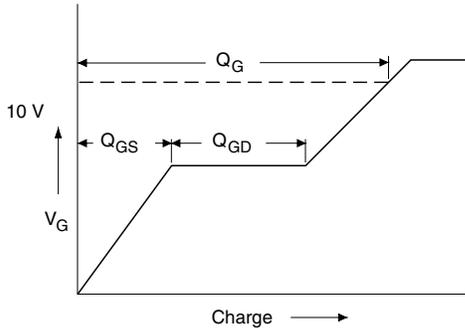


Fig. 13a - Basic Gate Charge Waveform

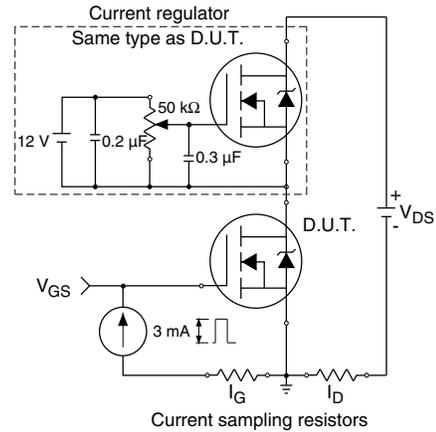
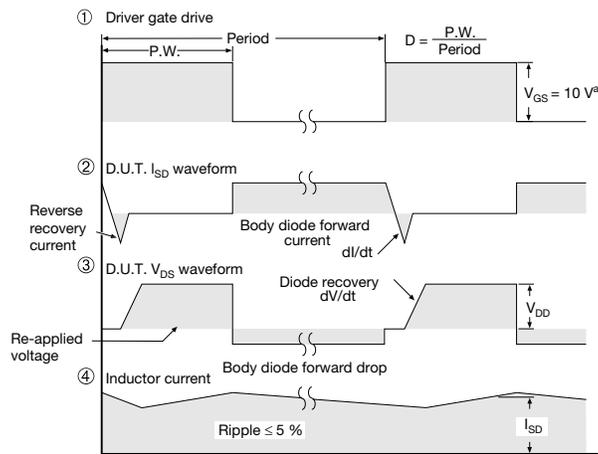
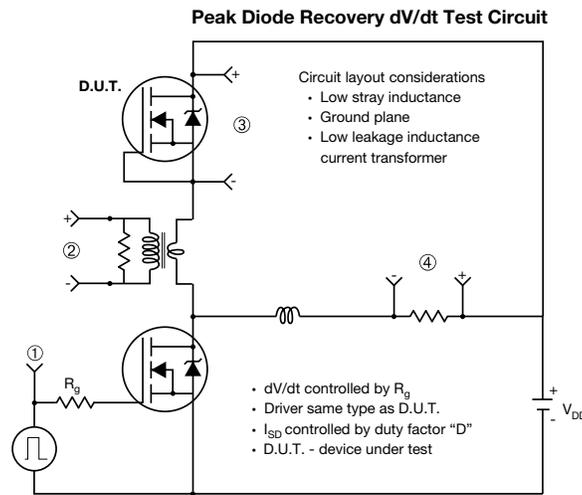


Fig. 13b - Gate Charge Test Circuit



Note  
a.  $V_{GS} = 5V$  for logic level devices

Fig. 14 - For N-Channel

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